

## Supplementary Information

# Modulated wafer-scale WS<sub>2</sub> films based on atomic-layer-deposition for various device applications

*Xiangyu Guo<sup>a</sup>, Hanjie Yang<sup>a</sup>, Xichao Mo<sup>b</sup>, Rongxu Bai<sup>a</sup>, Yanrong Wang<sup>b</sup>, Qi Han<sup>a</sup>,*

*Sheng Han<sup>a</sup>, Qingqing Sun<sup>a</sup>, David W. Zhang<sup>a</sup>, Shen Hu<sup>a,c,\*</sup> and Li Ji<sup>a,d,\*</sup>*

*<sup>a</sup> School of Microelectronics, Fudan University, Shanghai 200433, China; E-mail: hushen@fudan.edu.cn, lji@fudan.edu.cn*

*<sup>b</sup> School of Physical Science and Technology, Lanzhou University, Lanzhou 730000, China.*

*<sup>c</sup> Jiashan Fudan Institute, Jiashan 314100, China.*

*<sup>d</sup> Hubei Yangtze Memory Laboratories, Wuhan 430205, China.*

### **This PDF file includes:**

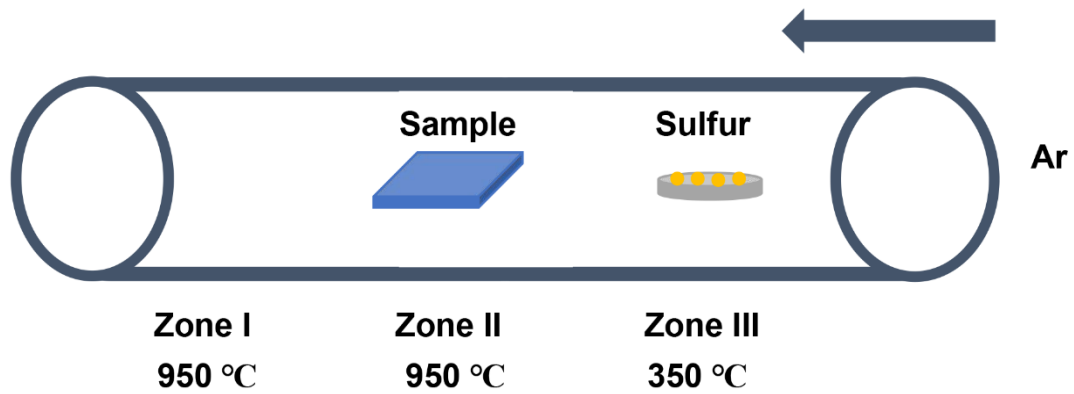
Fig. S1† The annealing process of WS<sub>2</sub> film.

Fig. S2† Detailed fabrication process of WS<sub>2</sub> FETs.

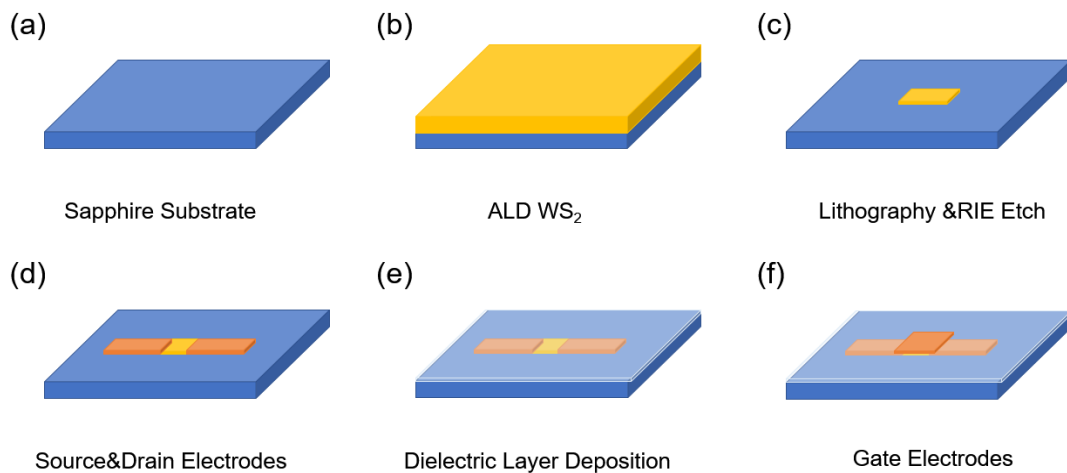
Fig. S3† Thickness of WS<sub>2</sub> with 200 ALD cycles.

Fig. S4 †SEM image of WS<sub>2</sub> film with 800 cycles.

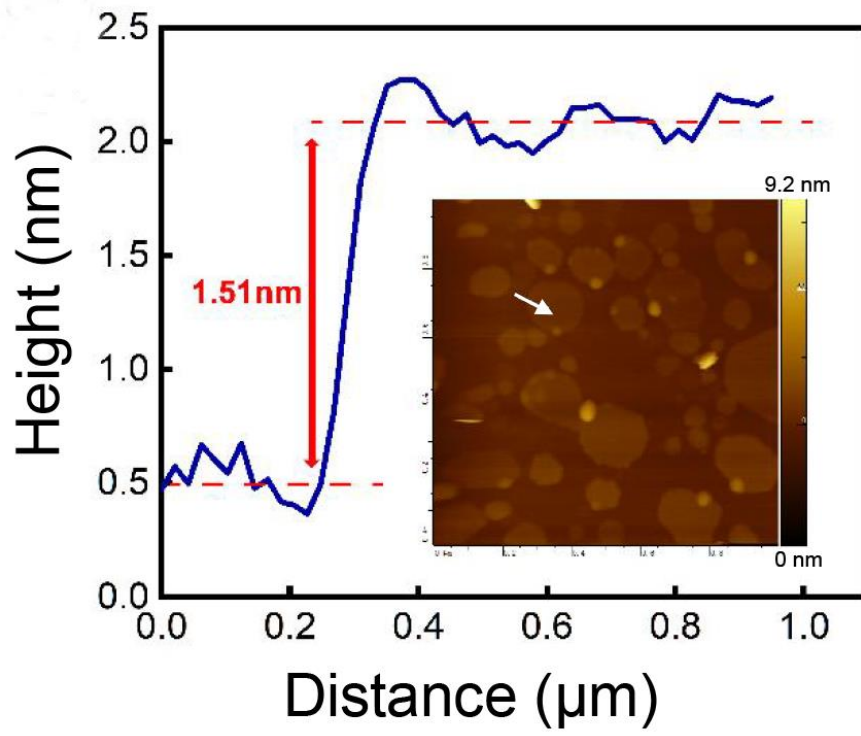
Fig. S5 †Process diagram of Nb-doped WS<sub>2</sub>.



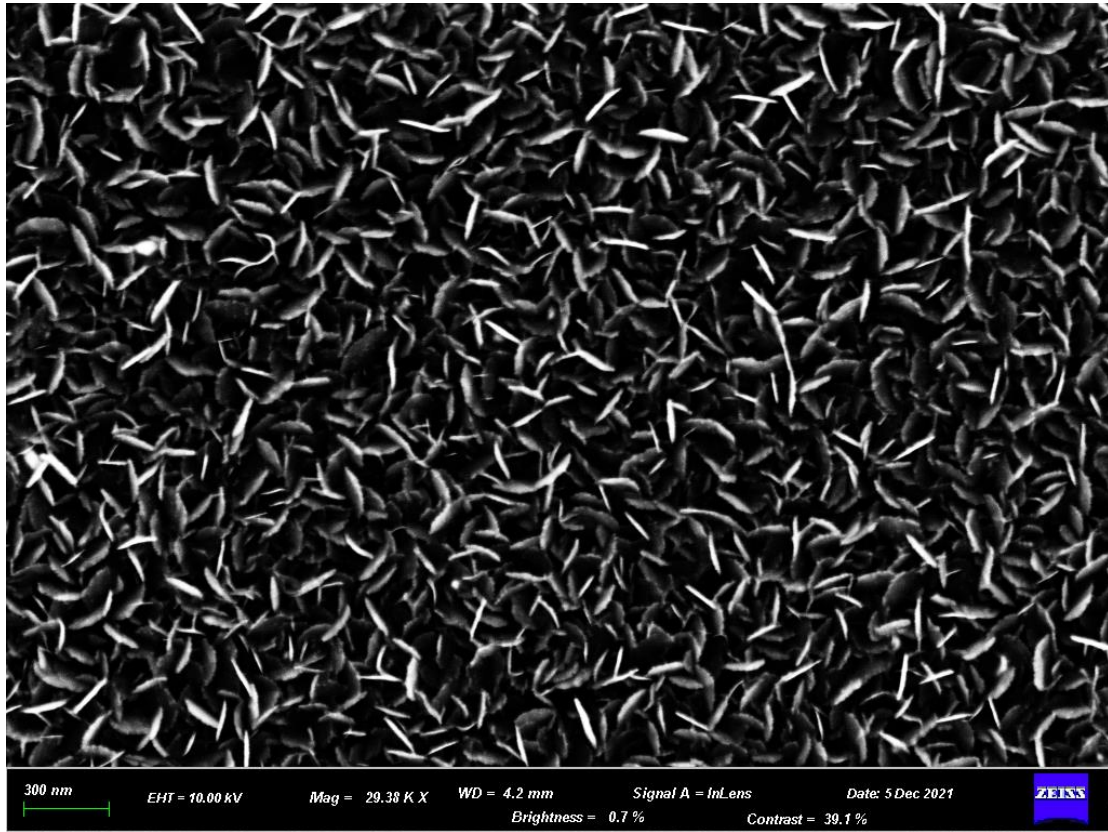
**Fig. S1** | The annealing process of WS<sub>2</sub> film. The as-deposited samples were placed in a quartz boat in the center of Zone II, and 0.5 g sulfur powder was placed in Zone III carried by a quartz boat. The distance of samples and sulfur powder is 30cm. Argon (10 sccm, 99.999%) was chosen as the carrier gas. The samples were annealed for 2 h in a 4-inch quartz tube at a base pressure of 10 Pa.



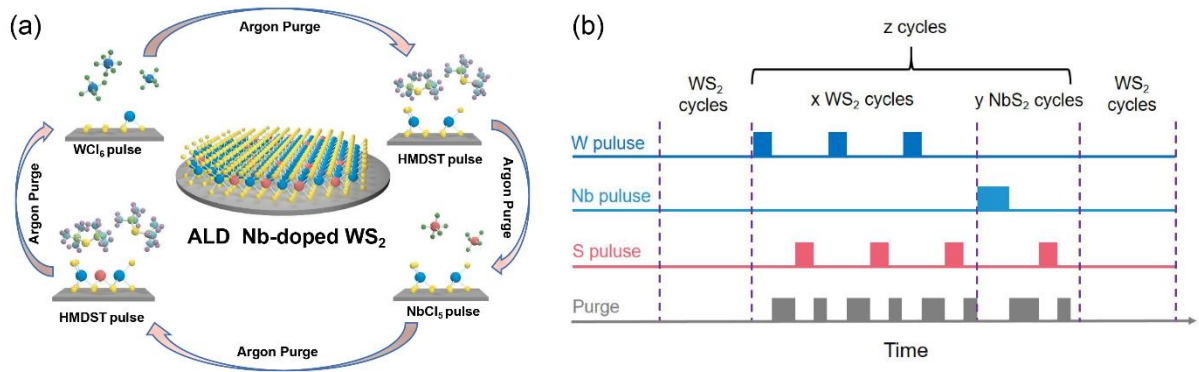
**Fig. S2** | Detailed fabrication process of WS<sub>2</sub> FETs. Top-gate FETs for WS<sub>2</sub> and Nb-doped WS<sub>2</sub> films were fabricated through CMOS-compatible processes. After annealing in S atmosphere, photolithography was used to define channel area and was etched by CF<sub>4</sub>/Ar (20/10 sccm) in RIE. Source and drain electrodes were patterned by photolithography and metalized by Ti/Au (10/70 nm) for WS<sub>2</sub> N-FETs and Ti/Pt (10/70 nm) for Nb-doped WS<sub>2</sub> P-FETs via PVD. Al<sub>2</sub>O<sub>3</sub> gate oxide was deposited by ALD at 250 °C. The precursors for Al<sub>2</sub>O<sub>3</sub> were TMA and H<sub>2</sub>O, respectively. After top-gate patterning, 10/70 nm Ti/Au was deposited by PVD.



**Fig. S3** | Thickness of WS<sub>2</sub> with 200 ALD cycles.



**Fig. S4** | SEM image of  $WS_2$  film with 800 cycles.



**Fig. S5** | Process diagram of Nb-doped  $WS_2$ . The Nb doping process consists of  $z$  large cycles, and every large cycle contains  $x$  cycles of  $WS_2$  and  $y$  cycles of  $NbS_2$ .